



100V N-Channel MOSFETs

General Description

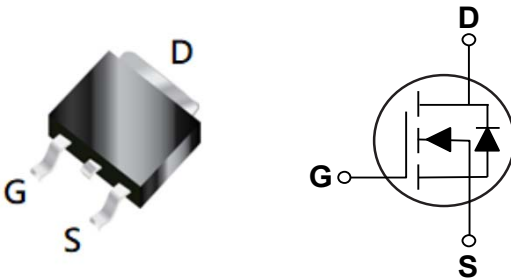
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV_{DSS}	$R_{DS(ON)}$	I_D
100 V	85 m Ω	15.65 A

Features

- $R_{DS(ON)} \leq 85m\Omega @ V_{GS}=10V$
- Improved dv/dt Capability
- Fast Switching
- Green Device Available

TO-252 Pin Configuration



Applications

- Lithium Battery Protection
- Wireless Impact
- Mobile Phone Fast Charging

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current - Continuous ($T_C=25^\circ\text{C}$)	15.65	A
I_{DM}	Drain Current - Pulsed (NOTE 1)	57.9	A
P_D	Power Dissipation ($T_C=25^\circ\text{C}$)	24.5	W
EAS	Single Pulse Avalanche Energy (NOTE 2)	2.45	mJ
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
Marking Code		NM085	

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	55	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	5.1	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu\text{A}$	100	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=100V, V_{GS}=0V$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=5A$	---	---	85	m Ω
		$V_{GS}=4.5V, I_D=3A$	---	---	100	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	1.2	---	2.5	V
gfs	Forward Transconductance	$V_{DS}=5V, I_D=5A$	---	14	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q_g	Total Gate Charge	$V_{DS}=50V, V_{GS}=10V, I_D=5A$	---	11.9	---	nC
Q_{gs}	Gate-Source Charge		---	2.8	---	
Q_{gd}	Gate-Drain Charge		---	1.7	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DS}=30V, V_{GS}=10V, R_G=1.8\Omega, I_D=5A$	---	3.8	---	nS
T_r	Rise Time		---	25.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	16	---	
T_f	Fall Time		---	8.8	---	
C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	1100	---	pF
C_{oss}	Output Capacitance		---	55	---	
C_{rss}	Reverse Transfer Capacitance		---	40	---	
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	3	---	Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	14.6	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=10A$	---	---	1.2	V

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=80V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=7A$.
3. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Characteristics Curves

FIG. 1- I_D vs. T_C

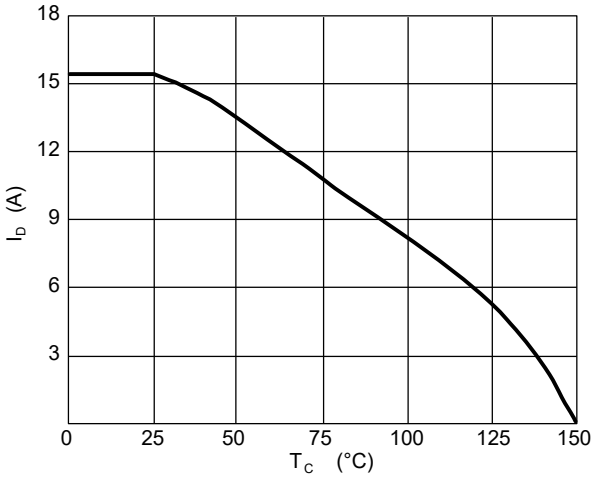


FIG. 2- $R_{DS(ON)}$ vs. V_{GS}

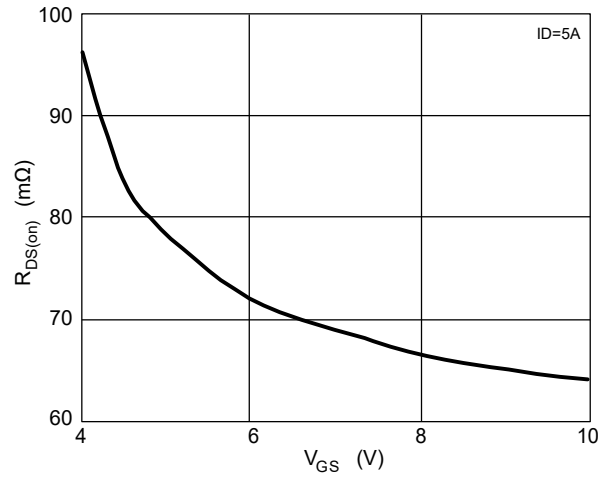


FIG. 3-Normalized $V_{GS(th)}$ vs. T_J

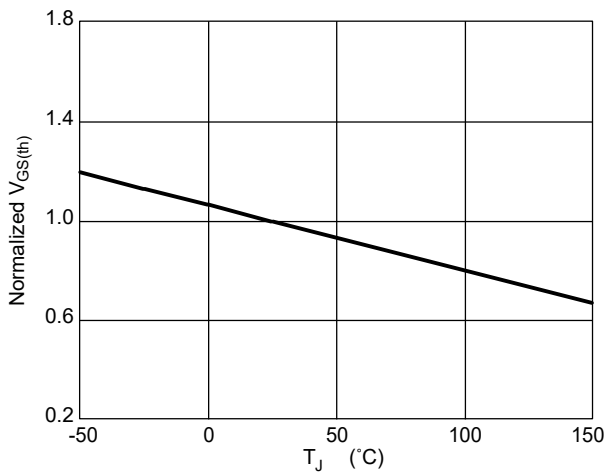


FIG. 4-Normalized $R_{DS(ON)}$ vs. T_J

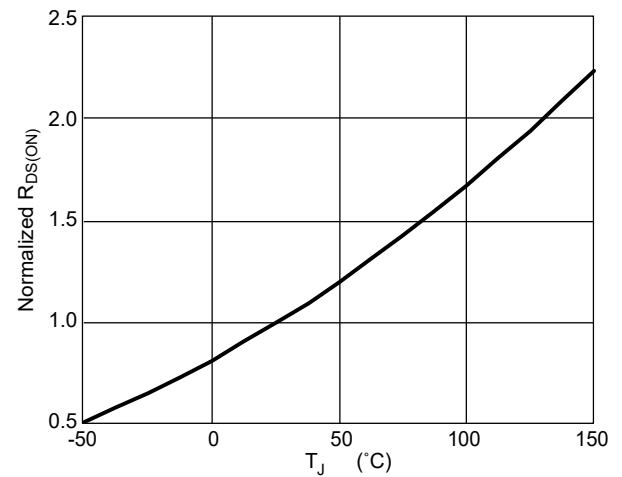


FIG. 5- I_S vs. V_{SD}

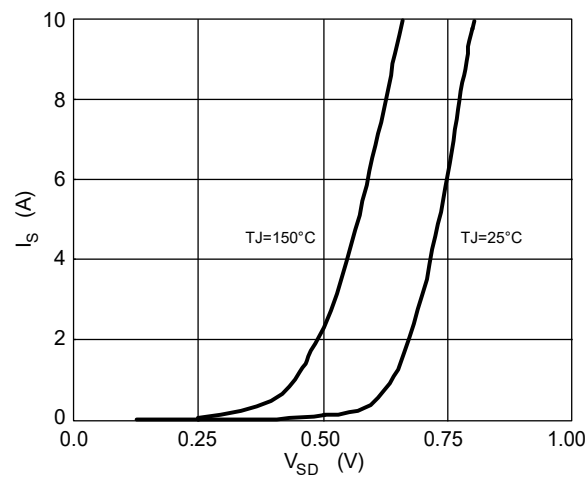
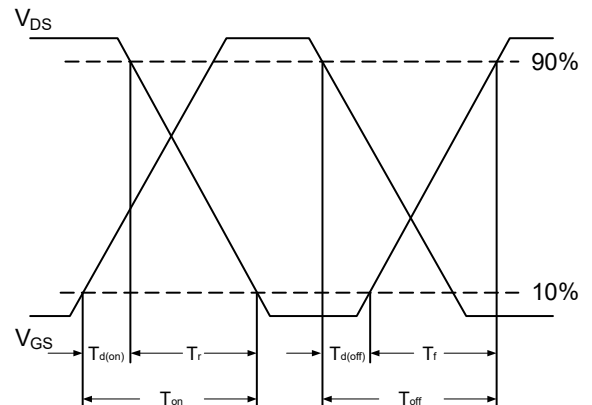


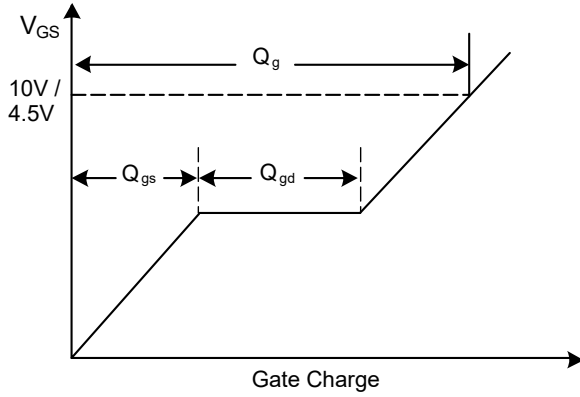
FIG. 6-Switching Time Waveform



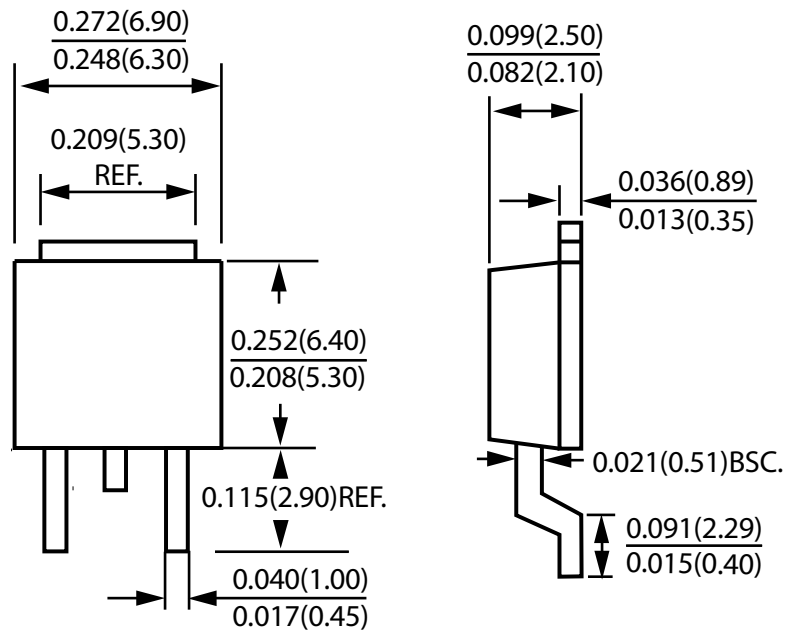


Characteristics Curves

FIG. 7-Gate Charge Waveform



Package Outline Dimensions



TO-252

Dimensions in inches and (millimeters)



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